

300mW Audio Power Amplifier with Shutdown Mode

FEATURES

- 1.0% (Max) THD at 1kHz at 300mW Continuous Average Output Power into 8Ω
- 1.0% (Max) THD at 1kHz at 300mW Continuous Average Output Power into 16Ω
- Shutdown Current 0.1μA (typ)
- MSOP Packaging
- No Output Coupling Capacitors, Bootstrap Capacitors, or Snubber Circuits are Necessary
- Unity-gain Stable
- External Gain Configuration Capability
- 300mW Output Power Guaranteed
- Single Supply Operation

APPLICATIONS

- Cellular Phones
- Personal Computers
- General Purpose Audio

TYPICAL OPERATING CIRCUIT

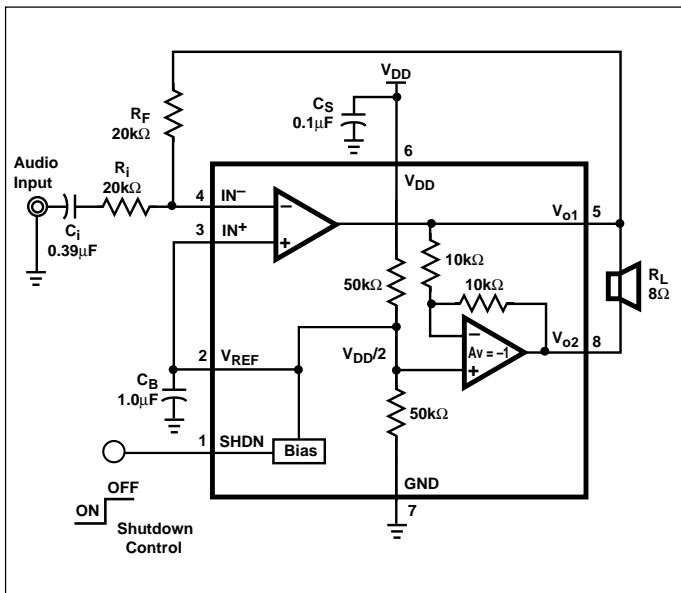


Figure 1

GENERAL DESCRIPTION

The TC4864 is a bridged audio power amplifier capable of delivering 300 mW of continuous average power into an 8Ω load with 1% (THD) from a 5V power supply.

The TC4864 audio power amplifier is specifically designed to provide high quality output power from a low supply voltage, while requiring very few external components.

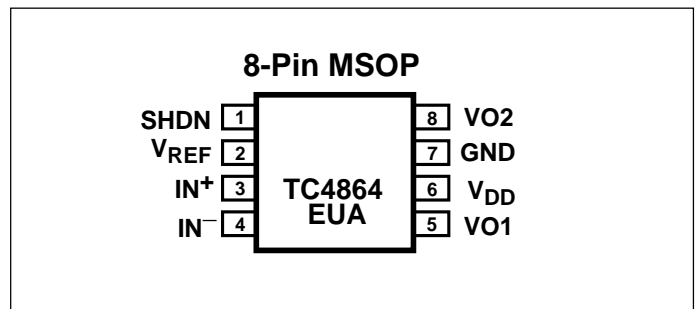
The TC4864 does not require output coupling, or bootstrap, capacitors; nor does it require snubber networks. Because of this, it is ideal for low-power portable applications.

The TC4864 features an externally controlled, low power consumption shutdown mode (Active High). The closed loop response of the unity-gain stable TC4864 can be configured by external gain-setting resistors. The device is offered in a space-saving 8-Pin MSOP package to suit applications where minimal board space layouts are essential. The TC4864 operates over an input supply voltage range of 2.7V to 5.5V.

ORDERING INFORMATION

Part Number	Package	Temp. Range
TC4864EUA	8-Pin MSOP	-40°C to +85°C

PIN CONFIGURATION



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ABSOLUTE MAXIMUM RATINGS*

Supply Voltage	6.0V
Storage Temperature	-65°C to +150°C
Input Voltage	-0.3V to $V_{DD} + 0.3V$
Power Dissipation	(Note 3)
ESD Susceptibility(Note 4)	3500V
ESD Susceptibility (Note 5)	250V
Junction Temperature	150°C
Soldering Information:	
Small Outline Package	
Vapor Phase (60 sec.)	215°C
Infrared (15 sec.)	220°C

Thermal Resistance

θ_{JC} (MSOP)	56°C/W
θ_{JA} (MSOP)	210°C/W

Operating Ratings

Temperature Range	
$T_{MIN} \leq T_A \leq T_{MAX}$	-40°C \leq T_A \leq +85°C
Supply Voltage	$2.7V \leq V_{DD} \leq 5.5V$

*Static-sensitive device. Unused devices must be stored in conductive material. Protect devices from static discharge and static fields. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to Absolute Maximum Rating Conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS: (Notes 1 and 2)

The following specifications apply for $V_{DD} = 5V$ unless otherwise specified. Limits apply for $T_A = 25^\circ C$

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I_{DD}	Quiescent Power Supply Current	$V_{IN} = 0V, I_O = 0A$ (Note 8)	—	4.1	9	mA
I_{SD}	Shutdown Current	$V_{PIN1} = V_{DD}$	—	0.1	1	μA
V_{OS}	Output Offset Voltage	$V_{IN} = 0V$	—	5	30	mV
P_O	Output Power	THD + N = 1% (max); f = 1kHz; $R_L = 8\Omega$ (Note 9)	300	740	—	mW
		THD+N = 1%(max); f=1kHz; $R_L = 16\Omega$	—	590	—	mW
THD+N	Total Harmonic Distortion+Noise	$P_O = 300mW; A_{VD} = 2; R_L = 8\Omega;$ $20Hz \leq f \leq 20kHz$	—	0.1	—	%
PSRR	Power Supply Rejection Ratio	$V_{DD} = 4.9V - 5.1V$	55	75	—	dB
V_{IH}	Shutdown High Level Input Voltage		2.5	—	—	V
V_{IL}	Shutdown Low Level Input Voltage		—	—	0.8	V

ELECTRICAL CHARACTERISTICS: (Notes 1 and 2)

The following specifications apply for $V_{DD} = 3V$ unless otherwise specified. Limits apply for $T_A = 25^\circ C$

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I_{DD}	Quiescent Power Supply Current	$V_{IN} = 0V, I_O = 0A$ (Note 8)	—	2.8	6.5	mA
I_{SD}	Shutdown Current	$V_{PIN1} = V_{DD}$	—	0.1	1	μA
V_{OS}	Output Offset Voltage	$V_{IN} = 0V$	—	5	—	mV
P_O	Output Power	THD = 1% (max); f = 1 kHz; $R_L = 8\Omega$	—	240	—	mW
		THD = 1% (max); f = 1 kHz; $R_L = 16\Omega$	—	200	—	mW
THD+N	Total Harmonic Distortion+Noise	$P_O = 100 mW; A_{VD} = 2; R_L = 8\Omega;$ $20Hz \leq f \leq 20kHz$	—	0.1	—	%
PSRR	Power Supply Rejection Ratio	$V_{DD} = 2.9V - 3.1V$	55	75	—	dB
V_{IH}	Shutdown High Level Input Voltage		1.6	—	—	V
V_{IL}	Shutdown Low Level Input Voltage		—	—	0.8	V

ELECTRICAL CHARACTERISTICS: (Notes 1 and 2) (Continued)

- Note 1:** All voltages are measured with respect to the ground pin, unless otherwise specified.
- Note 2:** Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given; however, the typical value is a good indication of device performance.
- Note 3:** The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{JMAX} , θ_{JA} , and the ambient temperature T_A . The maximum allowable power dissipation is $P_{DMAX} = (T_{JMAX} - T_A) / \theta_{JA}$. For the TC4864, $T_{JMAX} = 150^\circ\text{C}$. The typical junction-to-ambient thermal resistance, when board mounted, is 210°C/W for the MSOP package.
- Note 4:** Human body model, 100pF discharged through a 1.5 k Ω resistor.
- Note 5:** Machine Model, 220pF –240pF discharged through all pins.
- Note 6:** Typical values are measured at 25°C and represent the parametric norm.
- Note 7:** Limits are guaranteed to TelCom's AOQL (Average Outgoing Quality Level).
- Note 8:** The quiescent power supply current depends on the offset voltage when a practical load is connected to the amplifier.
- Note 9:** The power dissipation limitation for the package occurs at 300mW of output power. This package limitation is based on 25°C ambient temperature and $\theta_{JA} = 210^\circ\text{C/W}$. For higher output power possibilities refer to the Power Dissipation Section.

PIN DESCRIPTION

Pin No. (MSOP)	Symbol	Description
1	SHDN	Shutdown Logic Input.
2	V_{REF}	Reference Voltage Output ($V_{DD}/2$).
3	IN^+	Non-Inverting Input.
4	IN^-	Inverting Input.
5	V_{O1}	Non-Inverting Amplifier Output.
6	V_{DD}	Power Supply Input.
7	GND	Supply Power Return.
8	V_{O2}	Inverting Amplifier Output.

EXTERNAL COMPONENTS DESCRIPTION

Components		Functional Description
1	R_i	Inverting input resistance which sets the closed-loop gain in conjunction with R_F . This resistor also forms a high pass filter with C_i at $f_c = 1/(2\pi R_i C_i)$.
2	C_i	Input coupling capacitor which blocks the DC voltage at the amplifier's input terminals. Also creates a highpass filter with R_i at $f_c = 1/(2\pi R_i C_i)$. Refer to the section Proper Selection of External Components , for an explanation of how to determine the value of C_i .
3	R_F	Feedback resistance which sets the closed-loop gain in conjunction with R_i .
4	C_S	Supply bypass capacitor which provides power supply filtering. Refer to the Power Supply Bypassing section for information concerning proper placement and selection of the supply bypass capacitor.
5	C_B	Bypass pin capacitor which provides half-supply filtering. Refer to the Proper Selection of External Components for information concerning proper placement and selection of C_B .

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DETAILED DESCRIPTION

Application Information

Bridge Configuration Explanation

As shown in Figure 1, the TC4864 has two operational amplifiers internally, allowing for several different amplifier configurations.

The first amplifier's gain is externally configurable, while the second amplifier is internally fixed in a unity-gain, inverting configuration. The closed-loop gain of the first amplifier is set by selecting the ratio of R_F to R_i while the second amplifier's gain is fixed by the two internal 10k Ω resistors. Figure 1 shows that the output of amplifier one serves as the input to amplifier two which results in both amplifiers producing signals identical in magnitude, but out of phase 180°. Consequently, the differential gain for the IC is

$$A_{VD} = 2 \cdot (R_F/R_i)$$

The load is driven differentially through outputs V_{O1} and V_{O2} , creating an amplifier configuration commonly referred to as a "bridged mode". Bridged mode operation is different from the classical single-ended amplifier configuration where one side of its load is connected to ground.

There are several distinct advantages to having a bridge amplifier design as opposed to a single-ended configuration. First, the bridge design provides differential drive to the load, thus doubling output swing for a predetermined supply voltage. Second, it is possible to generate four times the output power as that of a single-ended amplifier under the same conditions, provided that the amplifier is not current limited or clipped. For information on how to choose an amplifier's closed-loop gain while avoiding excessive clipping, please refer to the **Audio Power Amplifier Design** section.

A bridge configuration, such as the one used in the TC4864, also creates a third advantage over single-ended amplifiers. Since the differential outputs, V_{O1} and V_{O2} , are biased at half-supply, no net DC voltage exists across the load. Thus, the need for an output coupling capacitor is eliminated in a bridge. As opposed to a single supply, single-ended amplifier configuration, in which the capacitor is a requirement. If an output coupling capacitor is not used in a single-ended configuration, the half-supply bias across the load would result in both increased internal IC power dissipation as well as permanent loudspeaker damage.

POWER DISSIPATION

Power dissipation is an important factor when designing a successful amplifier, whether the amplifier be bridged or single-ended. Equation 1 illustrates the maximum power dissipation point for a bridge amplifier operating at a given

supply voltage and driving a specified output load.

$$P_{DMAX} = (V_{DD})^2 / (2\pi^2 R_L) \quad \text{Single-Ended}$$

Equation 1.

However, a direct consequence of the increased power delivered to the load by a bridge amplifier is an increase in internal power dissipation point for a bridge amplifier operating under the same conditions.

$$P_{DMAX} = 4(V_{DD})^2 / (\pi^2 R_L) \quad \text{Bridge Mode}$$

Equation 2.

Since the TC4864 has two operational amplifiers in one package, the maximum internal power dissipation is 4 times that of a single-ended amplifier. Still, the TC4864 does not require heatsinking, even with this substantial increase in power dissipation. From Equation 1, assuming a 5V power supply and an 8 Ω load, the maximum power dissipation point is 625 mW. The maximum power dissipation point obtained from Equation 2 must not be greater than the power dissipation that results from Equation 3:

$$P_{DMAX} = (T_{JMAX} - T_A) / \theta_{JA}$$

Equation 3.

For the MSOP package, $\theta_{JA} = 210^\circ\text{C/W}$. $T_{JMAX} = 150^\circ\text{C}$ for the TC4864. Depending on the ambient temperature, T_A , of the system surroundings, Equation 3 can be used to find the maximum internal power dissipation supported by the IC packaging. If the result of Equation 2 is greater than that of Equation 3, either the supply voltage must be decreased, the load impedance must be increased, the ambient temperature reduced, or, through heat-sinking, the θ_{JA} must be lowered.

In a lot of cases, larger traces near the output, V_{DD} , and GND pins can be used to lower the θ_{JA} . The larger areas of copper serve as a form of heatsinking, allowing a higher power dissipation. For the typical application of a 5V power supply, with an 8 Ω load, the maximum ambient temperature possible without exceeding the maximum junction temperature, is approximately 44°C. (Provided that the device operation is around the maximum power dissipation point and assuming surface mount packaging.) Internal power dissipation is a function of output power. If typical operation is not around the maximum power dissipation point, the ambient temperature can be increased. For power dissipation information for lower output powers, refer to the **Typical Performance Characteristics** curves.

Power Supply Bypassing

As with any power amplifier, proper supply bypassing is essential for low noise performance and high power supply rejection. The location of the capacitor on both the bypass and power supply pins should be as near the device as possible. A larger half supply bypass capacitor has the effect of improved PSRR due to increased half-supply stability. Typical applications use a 5V regulator with 10 μ F and a 0.1 μ F bypass capacitor which aids in supply stability, but does not eliminate the need for bypassing the supply nodes of the TC4864. The selection of bypass capacitors, especially C_B , is thus dependent upon desired PSRR requirements, click and pop performance (as explained in the **Proper Selection of External Components** section), system cost, and size limitations.

Shutdown Function

The TC4864 contains a shutdown pin to externally turn off the amplifier's bias circuitry in order to reduce power consumption while not in use. This feature turns the amplifier off when a logic high is placed on the shutdown pin. Typically, half supply is the trigger point between a logic low and logic high level. To provide maximum device performance, it's best to switch between the V_{IL} and V_{IH} limits specified in the Electrical Characteristics tables. By switching the shutdown pin to V_{DD} , the TC4864 supply current draw will be minimized in the shutdown mode. While the device may be disabled with shutdown pin voltages less than the minimum V_{IH} , the shutdown current may be greater than the typical value of 0.1 μ A. Regardless of the conditions, the shutdown pin should be tied to a definite voltage so as to avoid unwanted state changes.

In many applications, a microcontroller or microprocessor output is used to control the shutdown circuitry which provides a quick, smooth transition into shutdown. Another solution is to use a single-pole, single-throw switch in tandem with an external pull-up resistor. When the switch is closed, the shutdown pin is connected to ground and enables the amplifier. Conversely, if the switch is open, the external pull-up resistor will disable the TC4864. This design ensures that the shutdown pin will not float, thus preventing undesirable state changes.

Proper Selection of External Components

Proper selection of external components in applications employing integrated power amplifiers is crucial in optimizing device and system performance. While the TC4864 is tolerant of a variety of external component combinations, consideration must be given to component values in order to maximize overall system quality.

The TC4864 is unity-gain stable, giving maximum system flexibility to the designer. The TC4864 is best used in low gain configurations to minimize THD+N values and maxi-

mize the signal to noise ratio. Low gain configurations require large input signals to obtain a specified output power. Audio CODECs are sources from which input signals equal to or greater than 1 V_{RMS} are available. For a more complete explanation of proper gain selection please refer to the section, **Audio Power Amplifier Design**.

In addition to gain, one of the major considerations is the closed-loop bandwidth of the amplifier. The bandwidth is dictated, to a large extent, by the choice of external components shown in Figure 1. The input coupling capacitor, C_i , forms a first order high pass filter which limits low frequency response. This value should be chosen based on needed frequency response for a few distinct reasons.

Selection of Input Capacitor Size

Large input capacitors are too bulky and less cost effective for portable designs. There is clearly a need for a space-saving capacitor to couple in low frequencies without drastic attenuation. But, in many cases, the speakers used in portable systems, whether internal or external, lack the ability to reproduce signals below 150Hz. In this specific case, employing a large input capacitor may not increase system performance.

In addition to system cost and size, click and pop performance is effected by the size of the input coupling capacitor, C_i . A larger input coupling capacitor requires more charge to reach its inactive DC voltage (nominally 1/2 V_{DD}). This charge comes from the output via the feedback and is apt to create pops upon enabling the device. Thus, by minimizing the capacitor size based on necessary low frequency response, turn-on pops are minimized.

Besides minimizing the input capacitor size, careful attention should be paid to the bypass capacitor value. Bypass capacitor, C_B is the most critical component in minimizing turn-on pops, since it determines how fast the TC4864 turns on. The slower the TC4864's outputs ramp to their quiescent DC voltage (nominally 1/2 V_{DD}), the smaller the turn-on pop. Choosing $C_B = 1.0\mu$ F along with a small value of C_i (in the range of 0.1 μ F to 0.39 μ F), should produce a clickless and popless shutdown function. While the device will function properly (no oscillations or motorboating) with $C_B = 0.1\mu$ F, the device will be much more susceptible to turn-on clicks and pops. Thus, a value of $C_B = 1.0\mu$ F or larger is recommended in all but the most cost sensitive designs.

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AUDIO POWER AMPLIFIER DESIGN

Design a 300mW/8Ω Audio Amplifier

Given:

Power Output	300mW
Load Impedance	8Ω
Input Level	1 V _{RMS}
Input Impedance	20kΩ
Bandwidth	100Hz – 20kHz ± 0.25dB

A designer must first determine the minimum supply rail to obtain the specified output power. By extrapolating from the Output Power vs Supply Voltage graphs in the **Typical Performance Characteristics** section, the supply rail can easily be found. Another way to determine the minimum supply rail is to calculate the required V_{OPEAK} using Equation 4 and add the dropout voltage. Using this method, the minimum supply voltage would be $(V_{OPEAK} + (2 \cdot V_{OD}))$, where V_{OD} is extrapolated from the Dropout Voltage vs Supply Voltage curve in the **Typical Performance Characteristics** section.

$$V_{OPEAK} = \sqrt{(2R_L P_O)}$$

Equation 4.

Using the Output Power vs Supply Voltage graph for an 8Ω load, the minimum supply rail is 3.5V. But since 5V is a standard supply voltage in most applications, it is chosen for the supply rail. Extra supply voltage creates a buffer that allows the TC4864 to reproduce peaks in excess of 500mW without producing audible distortion. At this point, the designer must ensure that the power supply choice and the output impedance does not violate the conditions set forth in the Power Dissipation section.

Once the power dissipation equations have been addressed, the required differential gain can be determined from Equation 5.

$$A_{VD} \geq \sqrt{P_O R_L} / (V_{IN}) = V_{ORMS} / V_{INRMS}$$
$$R_F / R_i = A_{VD} / 2$$

Equation 5.

From Equation 5, the minimum A_{VD} is 1.55; use $A_{VD} = 2$. Since the desired input impedance was 20kΩ, and with a A_{VD} of 2, a ratio of 1:1 of R_F to R_i results in an allocation of $R_i = R_F = 20k\Omega$. The final design step is to address the bandwidth requirements which must be stated as a pair of -3dB frequency points. Five times away from a pole gives 0.17dB down from passband response which is better than the required ±0.25dB specified.

$$f_L = 100\text{Hz}/5 = 20\text{Hz}$$
$$f_H = 20\text{kHz} \times 5 = 100\text{kHz}$$

As stated in the **External Components** section, R_i in conjunction with C_i create a highpass filter.

$$C_i \geq \frac{1}{2\pi R_i f_c}$$

$$C_i \geq 1/(2\pi \cdot 20k\Omega \cdot 20\text{Hz}) = 0.398\mu\text{F}; \text{ use } 0.39\mu\text{F}$$

The high frequency pole is determined by the product of the desired high frequency pole, f_H , and the differential gain, A_{VD} . With a $A_{VD} = 2$ and $f_H = 100\text{kHz}$, the resulting GBWP = 100kHz which is much smaller than the TC4864 GBWP of 18MHz. This figure illustrates a situation in which a designer needs to design an amplifier with a higher differential gain. The TC4864 can still be used without running into bandwidth problems.

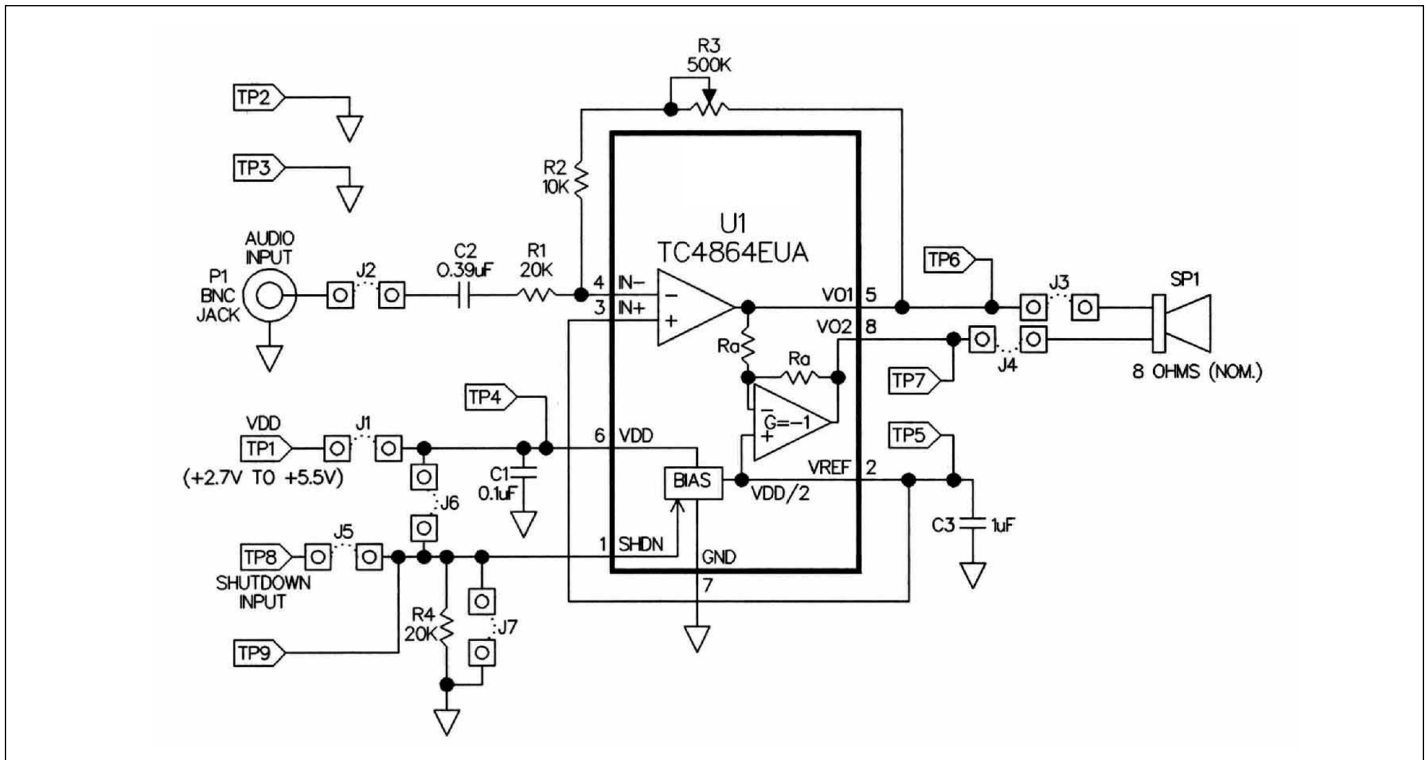


Figure 2. TC4864 Evaluation Board Schematic

TC4864 EVALUATION BOARD

The TC4864 Evaluation Board is a 2.5" x 3.5" circuit board containing a socketed TC4864 and all of the necessary external components required to drive a speaker in the bridged mode configuration. The board contains an eight-ohm speaker for user convenience, however an external speaker or resistive load can be connected to the TC4864's output stage through test points TP6 and TP7.

The evaluation board is fully assembled with the required external resistors, capacitors, and potentiometer which allow the user to adjust the differential voltage gain [i.e. $A_{VD} = (2 * (R2 + R3)) / R1$] and make dynamic audio measurements at the TC4864's driver outputs. For convenience, several test points and jumpers are available for measuring various voltages and currents on the circuit board.

Figure 2 is a schematic of the TC4864 Evaluation Board, and Figure 3 shows the assembly drawing and artwork for the board. Table 1 lists the voltages that are monitored by the test points and Table 2 lists the currents that can be measured as well as the various operating modes of the demo card using the jumpers on the board. NOTE: Never operate the TC4864 Evaluation Board with both J6 and J7 connected simultaneously! **Table 3 lists the differential voltage gain (A_{VD}) the user can set by adjusting potentiometer R3.**

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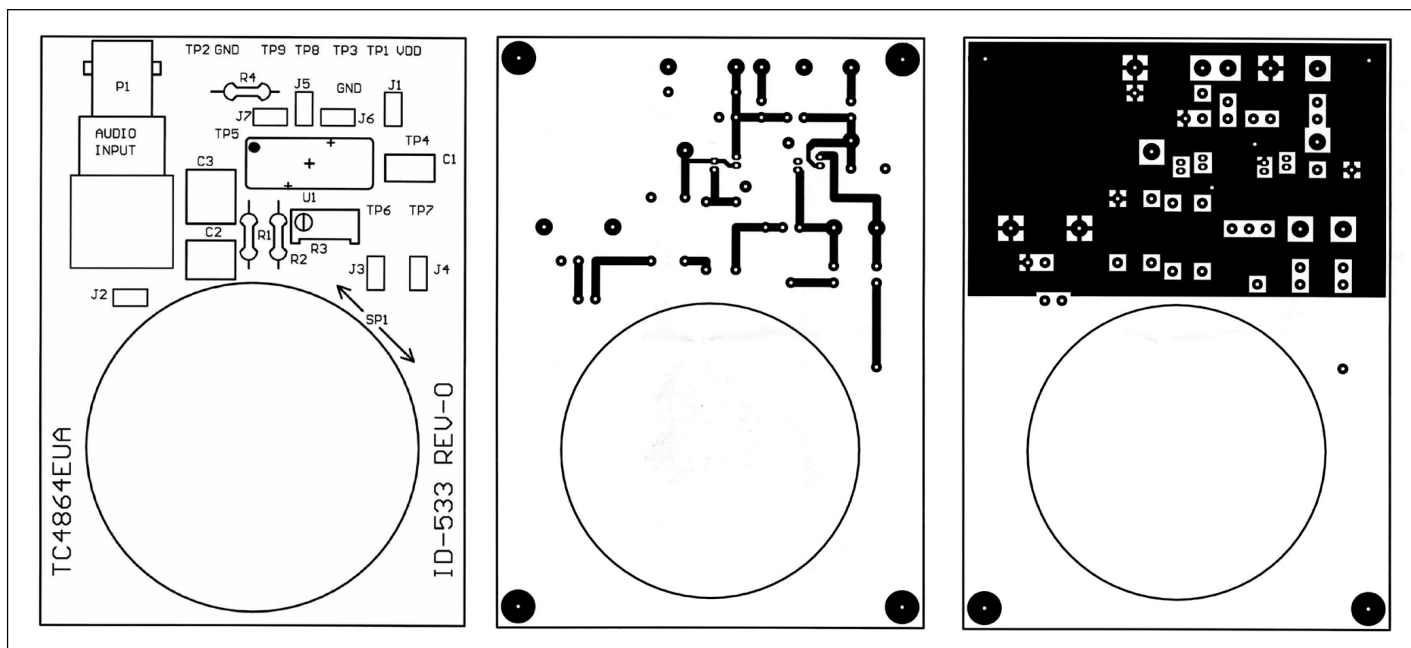


Figure 3. TC4864 Evaluation Assembly Drawing and Artwork

Table 1. TC4864 Evaluation Board Test Points

Test Point	Voltage Measurement
TP1	Evaluation Board Power Supply Input [+2.7V to +4.4V]
TP2	Ground
TP3	Ground
TP4	TC4864 V_{DD} Supply Voltage
TP5	TC4864 V_{REF} Output
TP6	TC4864 V_{O1} Amplifier Output
TP7	TC4864 V_{O2} Amplifier Output
TP8	Evaluation Board External Shutdown Input (Active High)
TP9	TC4864 Shutdown Input

Table 2. TC4864 Evaluation Board Jumpers

Test Point	Voltage Measurement
J1	TC4964 Evaluation Board Supply Current
J2	TC4964 Evaluation Board Input Audio Signal Supply Current
J3	TC4964 Evaluation Board Board V_{O1} Output Load Current
J4	TC4964 Evaluation Board Board V_{O2} Output Load Current
J5	TC4964 Evaluation Board Shutdown Input Current
J6	TC4964 Evaluation Board Disable (See Notes 1 and 2)
J7	TC4964 Evaluation Board Enable (See Notes 1 and 2)

NOTES:

- Never Connect Both J6 and J7 Jumpers Simultaneously.
- If Jumpers J6 AND J7 are both 'Open', The Evaluation Board will Default to the "Enable" Mode.

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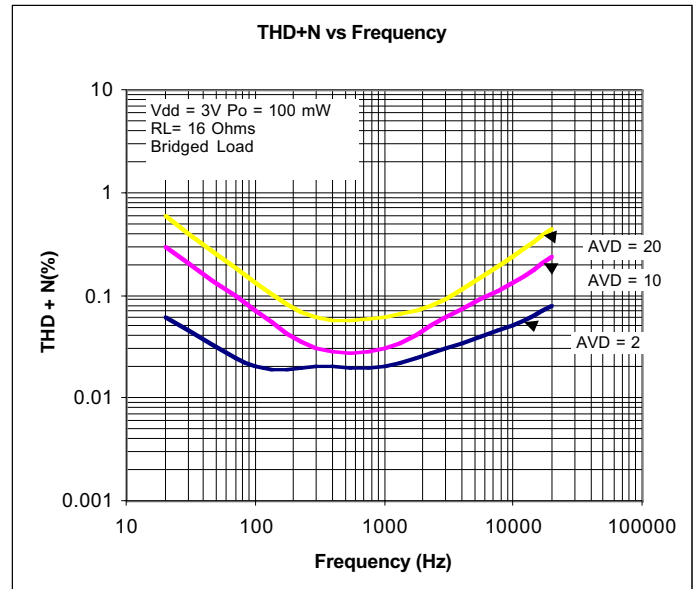
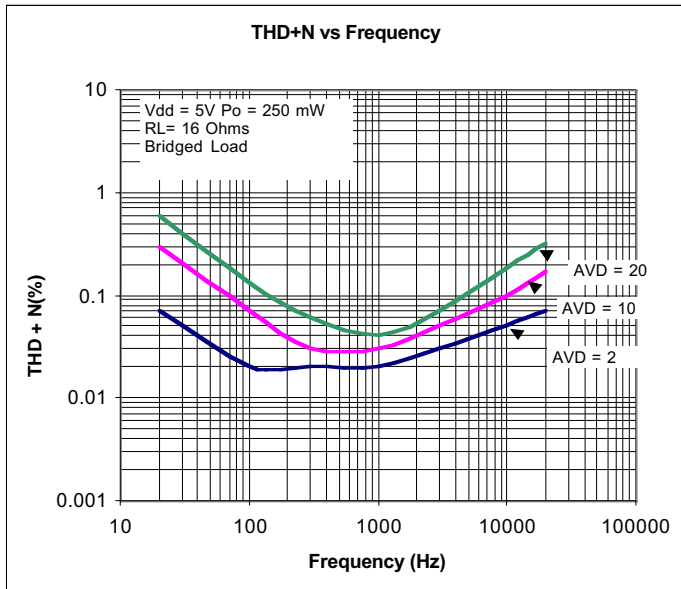
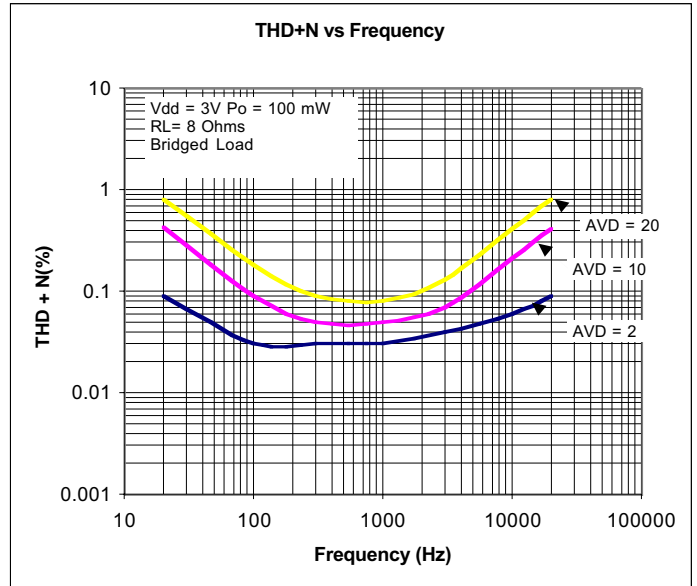
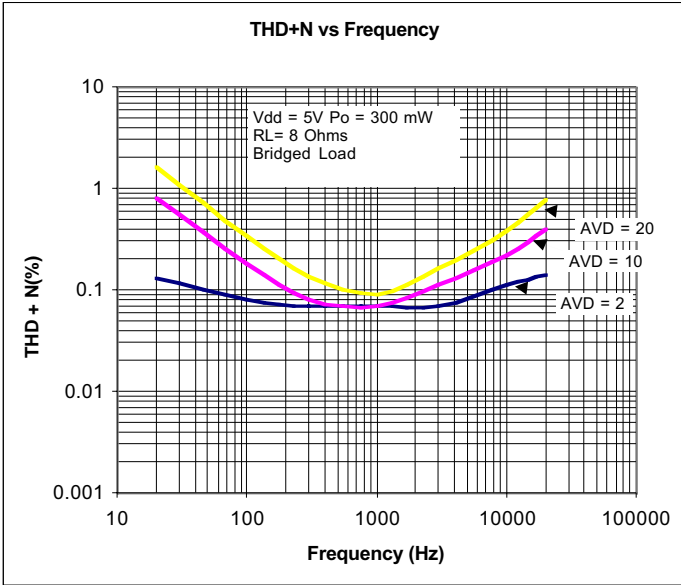
Table 3. TC4864 Evaluation Board A_{VD} Adjustments (Via R3)

R3 Setting (W)	Differential Voltage Gain (A_{VD})	A_{VD} (dB)
0	1	0
10K	2	6
25K	3.5	11
40K	5	14
60K	7	17
90K	10	20
150K	16	24
190K	20	26
240K	25	28
310K	32	30
340K	35	31
390K	40	32
440K	45	33
490K	50	34

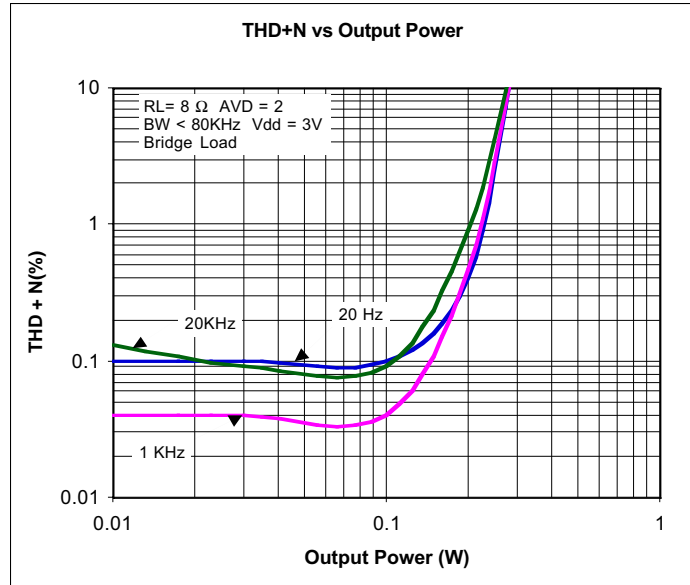
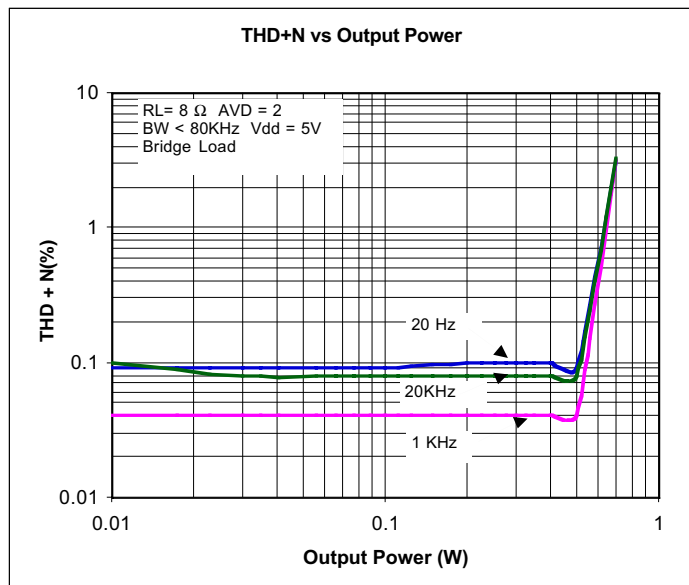
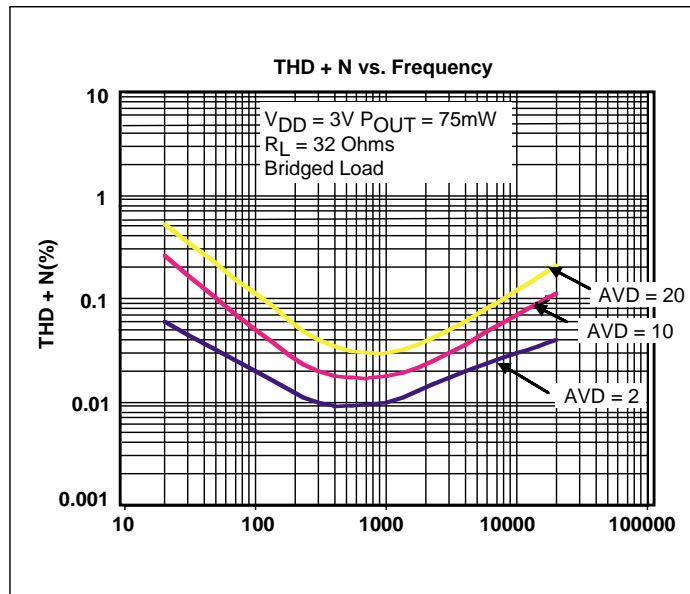
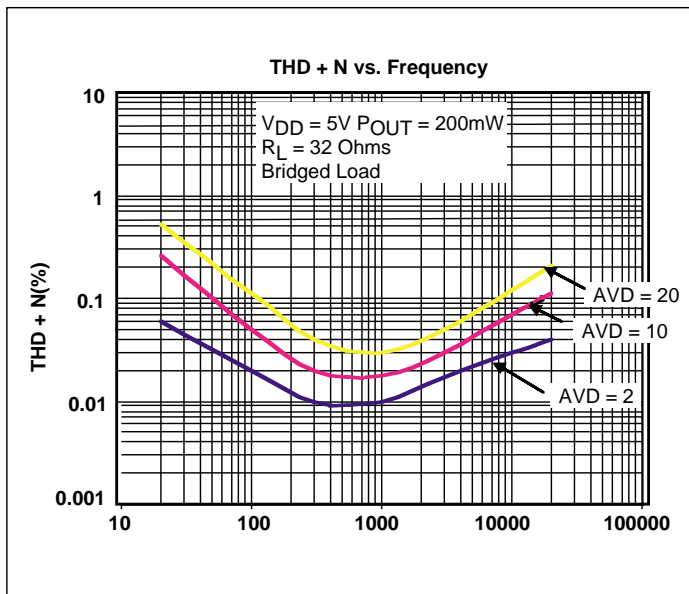
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TYPICAL CHARACTERISTICS



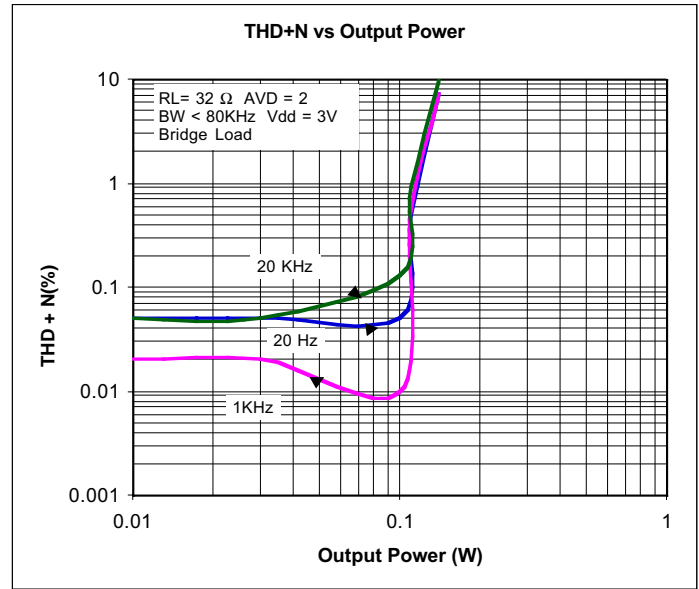
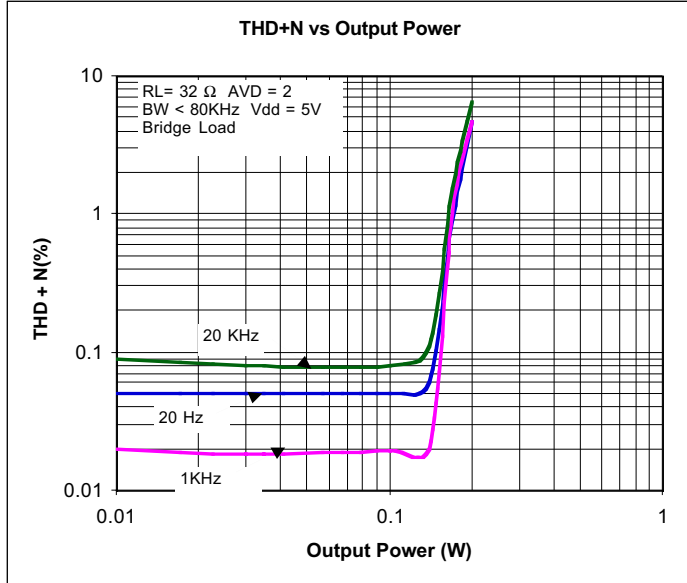
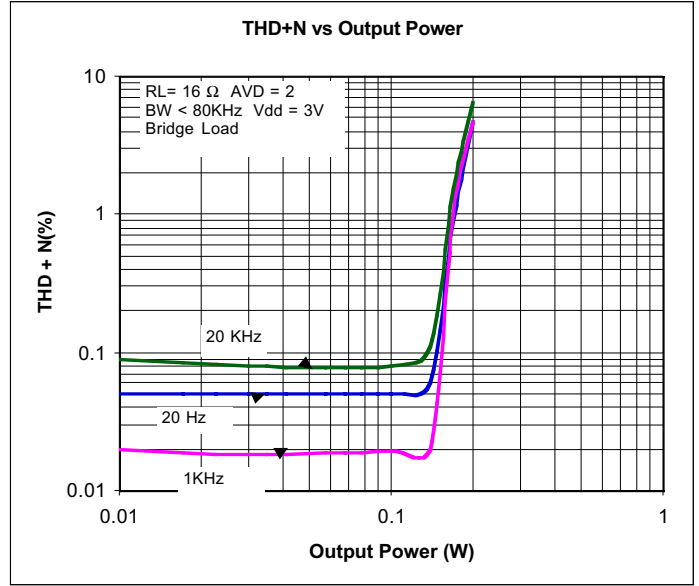
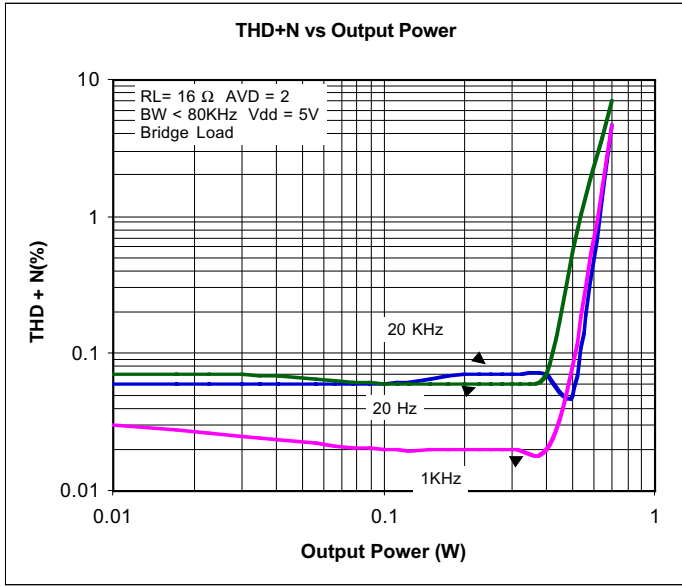
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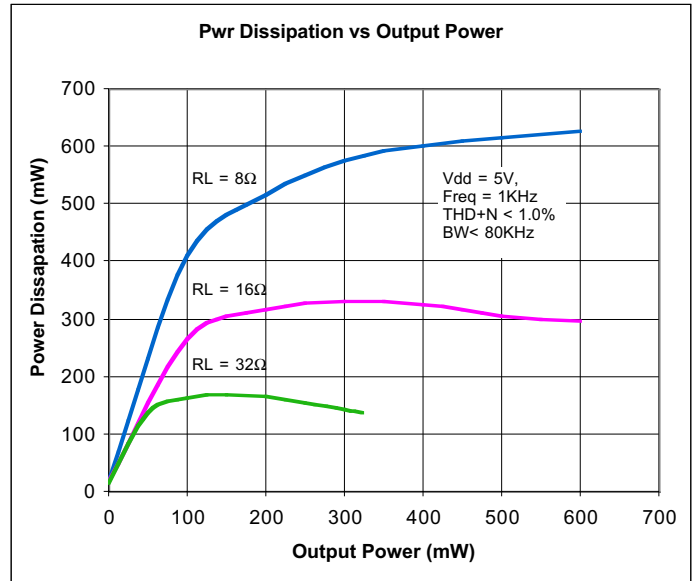
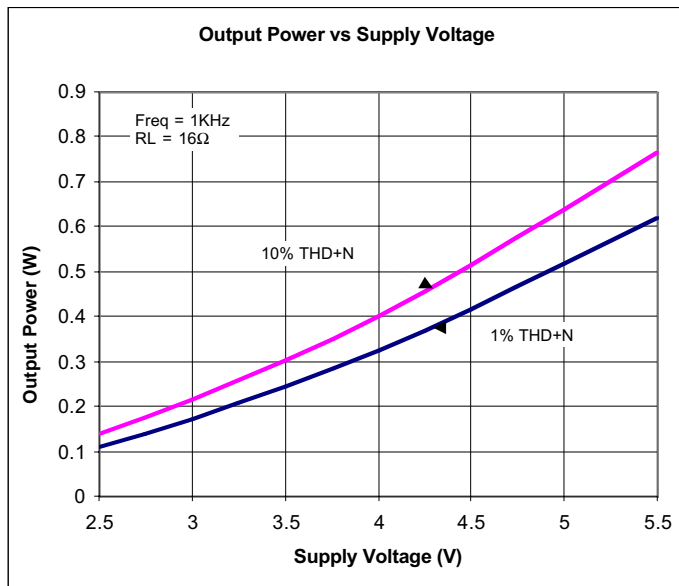
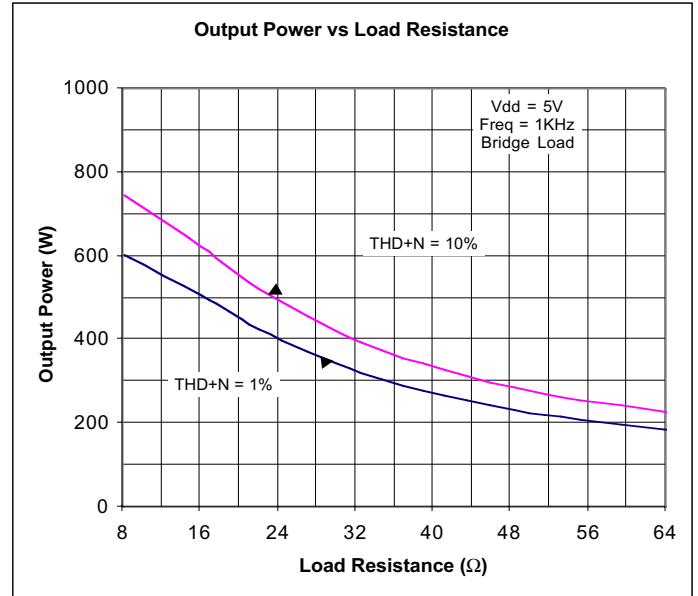
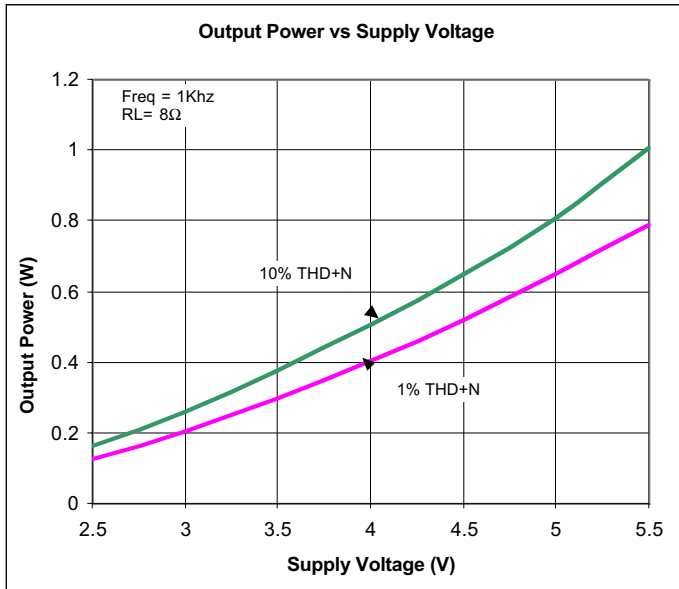
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TYPICAL CHARACTERISTICS



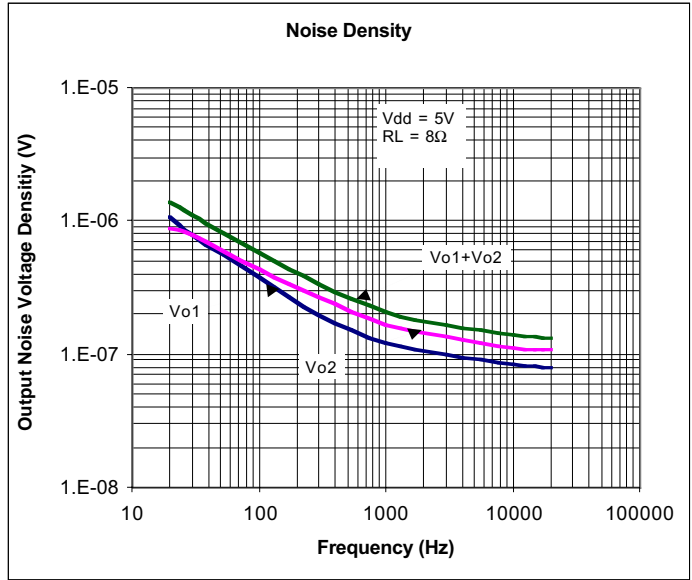
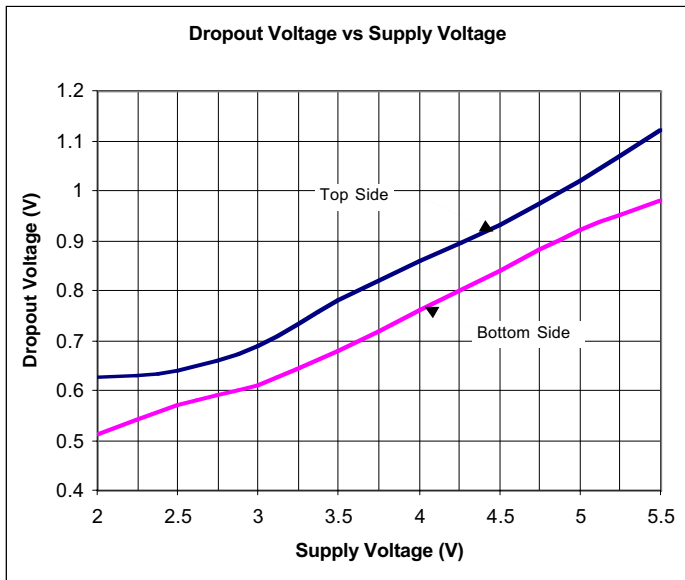
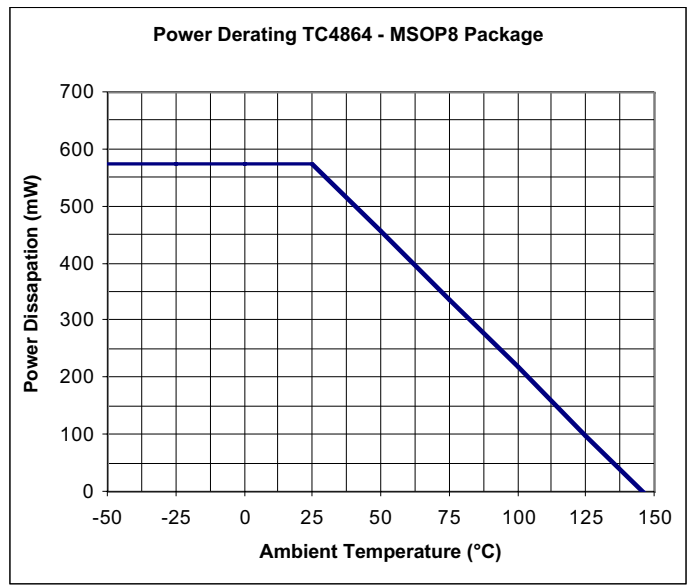
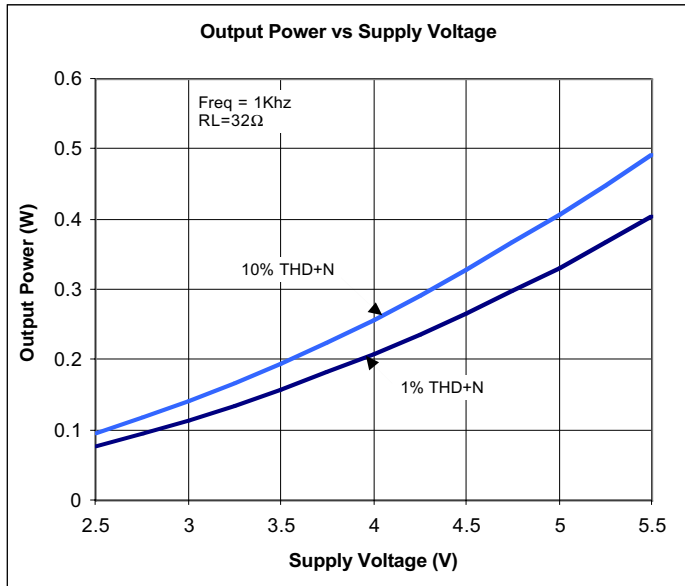
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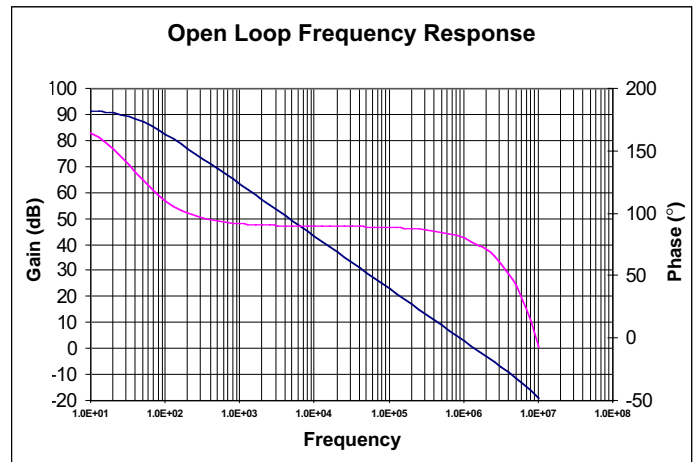
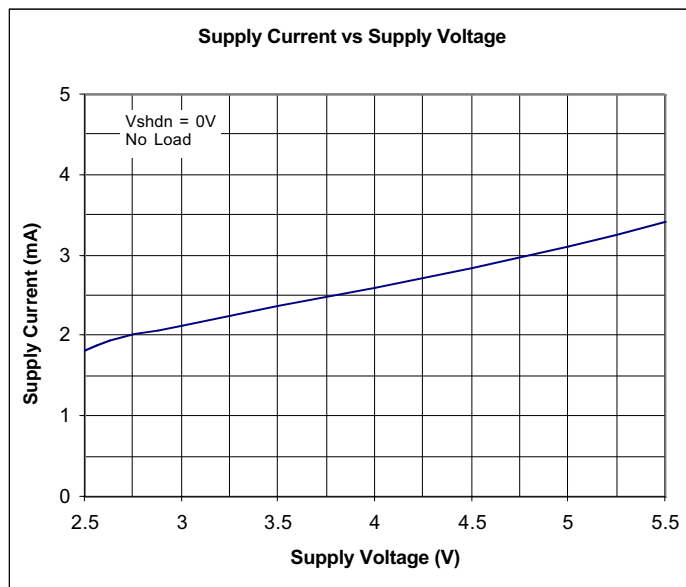
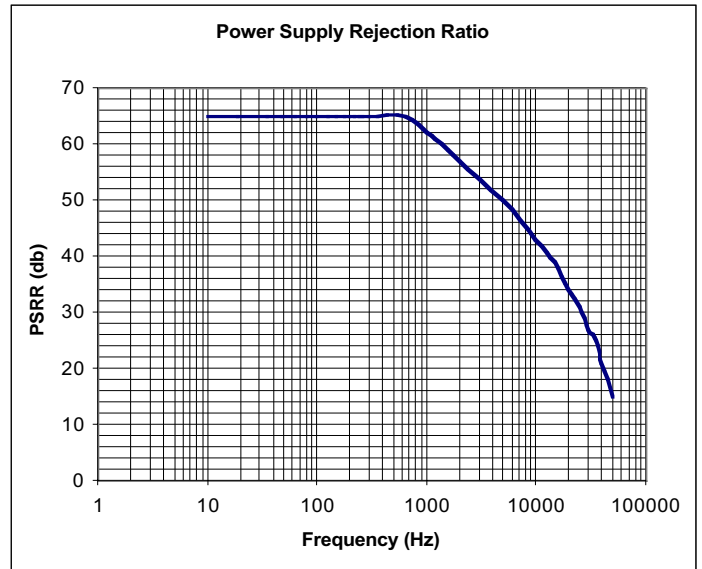
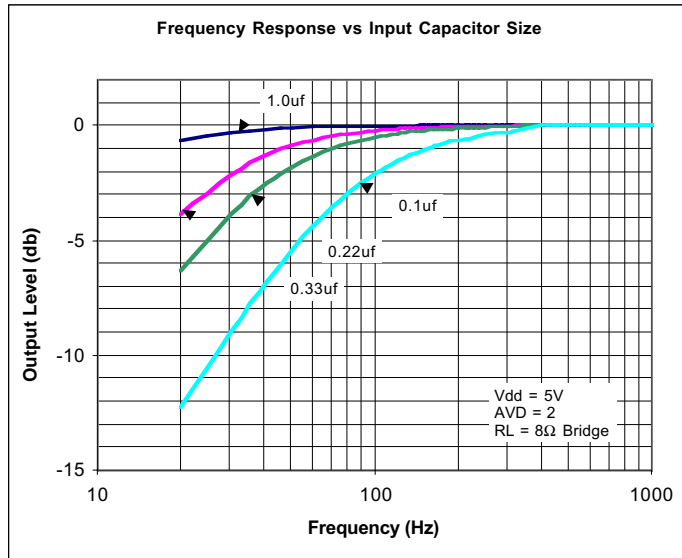
300mW Audio Power Amplifier with Shutdown Mode

TC4864

TYPICAL CHARACTERISTICS



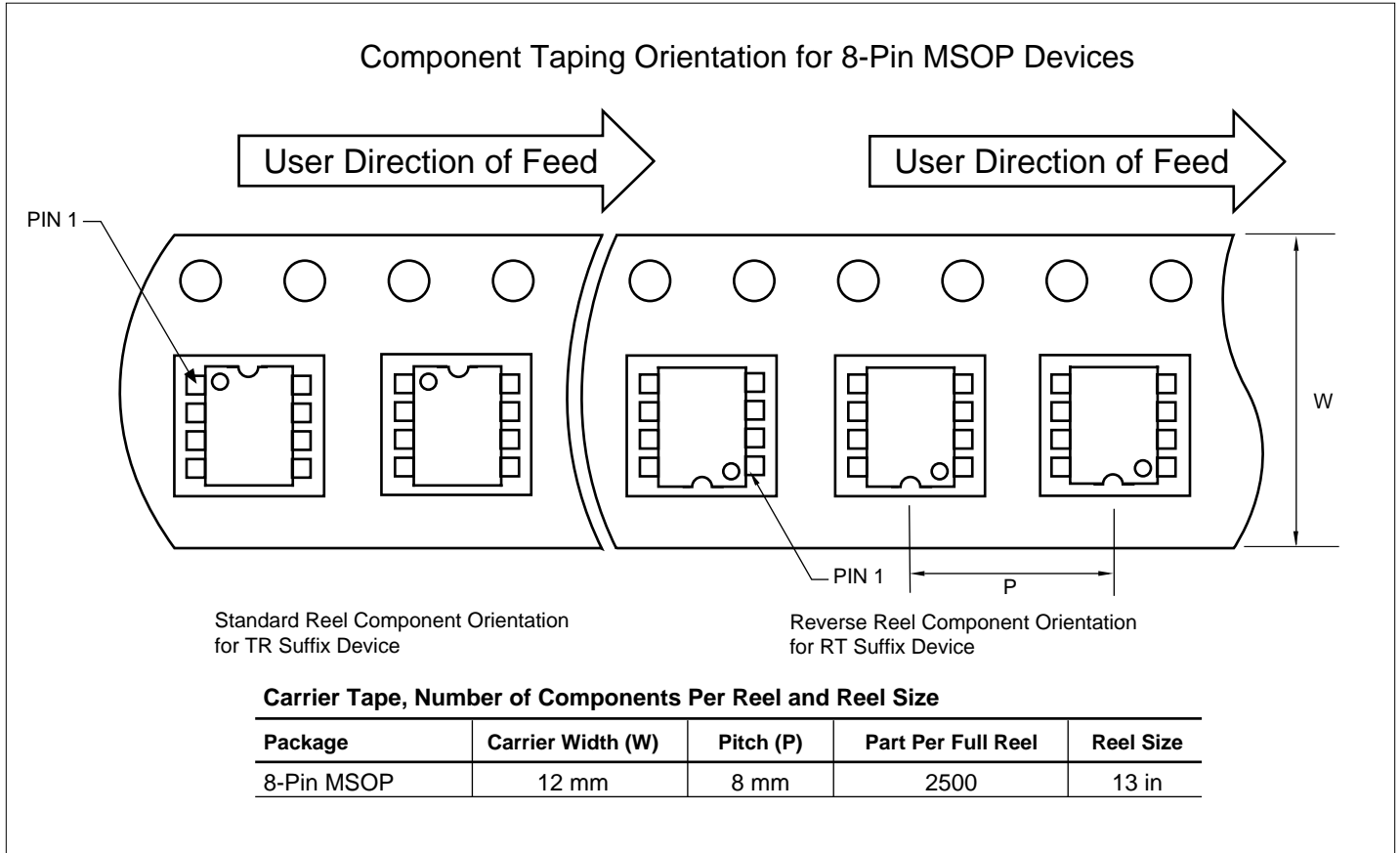
TYPICAL CHARACTERISTICS



300mW Audio Power Amplifier with Shutdown Mode

TC4864

TAPING FORM

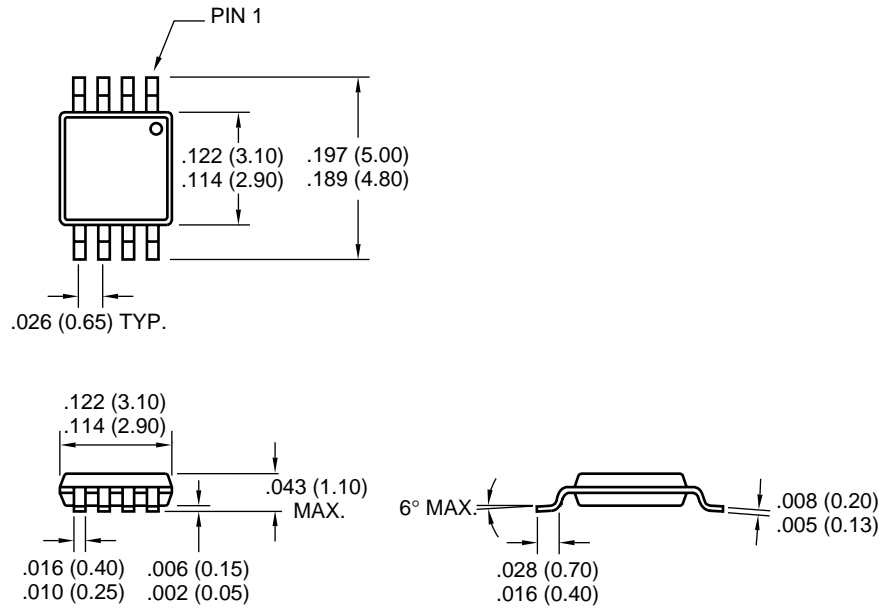


300mW Audio Power Amplifier with Shutdown Mode

TC4864

PACKAGE DIMENSIONS

8-Pin MSOP



Dimensions: inches (mm)



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200 Fax: 480-792-7277
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Web Address: <http://www.microchip.com>

Rocky Mountain

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Chandler, AZ 85224-6199
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Atlanta

500 Sugar Mill Road, Suite 200B
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Analog Product Sales
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Dallas

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Tel: 972-818-7423 Fax: 972-818-2924

Dayton

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Tel: 937-291-1654 Fax: 937-291-9175

Detroit

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Tel: 248-538-2250 Fax: 248-538-2260

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Mountain View

Analog Product Sales
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Mountain View, CA 94043-1836
Tel: 650-968-9241 Fax: 650-967-1590

New York

150 Motor Parkway, Suite 202
Hauppauge, NY 11788
Tel: 631-273-5305 Fax: 631-273-5335

San Jose

Microchip Technology Inc.
2107 North First Street, Suite 590
San Jose, CA 95131
Tel: 408-436-7950 Fax: 408-436-7955

Toronto

6285 Northam Drive, Suite 108
Mississauga, Ontario L4V 1X5, Canada
Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

China - Beijing

Microchip Technology Beijing Office
Unit 915
New China Hong Kong Manhattan Bldg.
No. 6 Chaoyangmen Beidajie
Beijing, 100027, No. China
Tel: 86-10-85282100 Fax: 86-10-85282104

China - Shanghai

Microchip Technology Shanghai Office
Room 701, Bldg. B
Far East International Plaza
No. 317 Xian Xia Road
Shanghai, 200051
Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

Hong Kong

Microchip Asia Pacific
RM 2101, Tower 2, Metroplaza
223 Hing Fong Road
Kwai Fong, N.T., Hong Kong
Tel: 852-2401-1200 Fax: 852-2401-3431

India

Microchip Technology Inc.
India Liaison Office
Divyasree Chambers
1 Floor, Wing A (A3/A4)
No. 11, OIShaughnessey Road
Bangalore, 560 025, India
Tel: 91-80-2290061 Fax: 91-80-2290062

Japan

Microchip Technology Intl. Inc.
Benex S-1 6F
3-18-20, Shinyokohama
Kohoku-Ku, Yokohama-shi
Kanagawa, 222-0033, Japan
Tel: 81-45-471-6166 Fax: 81-45-471-6122

Korea

Microchip Technology Korea
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku
Seoul, Korea
Tel: 82-2-554-7200 Fax: 82-2-558-5934

ASIA/PACIFIC (continued)

Singapore

Microchip Technology Singapore Pte Ltd.
200 Middle Road
#07-02 Prime Centre
Singapore, 188980
Tel: 65-334-8870 Fax: 65-334-8850

Taiwan

Microchip Technology Taiwan
11F-3, No. 207
Tung Hua North Road
Taipei, 105, Taiwan
Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

EUROPE

Australia

Microchip Technology Australia Pty Ltd
Suite 22, 41 Rawson Street
Epping 2121, NSW
Australia
Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

Denmark

Microchip Technology Denmark ApS
Regus Business Centre
Lautrup høj 1-3
Ballerup DK-2750 Denmark
Tel: 45 4420 9895 Fax: 45 4420 9910

France

Arizona Microchip Technology SARL
Parc d'Activité du Moulin de Massy
43 Rue du Saule Trapu
Batiment A - 1er Etage
91300 Massy, France
Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany

Arizona Microchip Technology GmbH
Gustav-Heinemann Ring 125
D-81739 Munich, Germany
Tel: 49-89-627-144 0 Fax: 49-89-627-144-44

Germany

Analog Product Sales
Lochhamer Strasse 13
D-82152 Martinsried, Germany
Tel: 49-89-895650-0 Fax: 49-89-895650-22

Italy

Arizona Microchip Technology SRL
Centro Direzionale Colleoni
Palazzo Taurus 1 V. Le Colleoni 1
20041 Agrate Brianza
Milan, Italy
Tel: 39-039-65791-1 Fax: 39-039-6899883

United Kingdom

Arizona Microchip Technology Ltd.
505 Eskdale Road
Winnersh Triangle
Wokingham
Berkshire, England RG41 5TU
Tel: 44 118 921 5869 Fax: 44-118 921-5820

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